

## PRODUCT SPECIFICATION FOR INFORMATION

FINAL SPECIFICATION

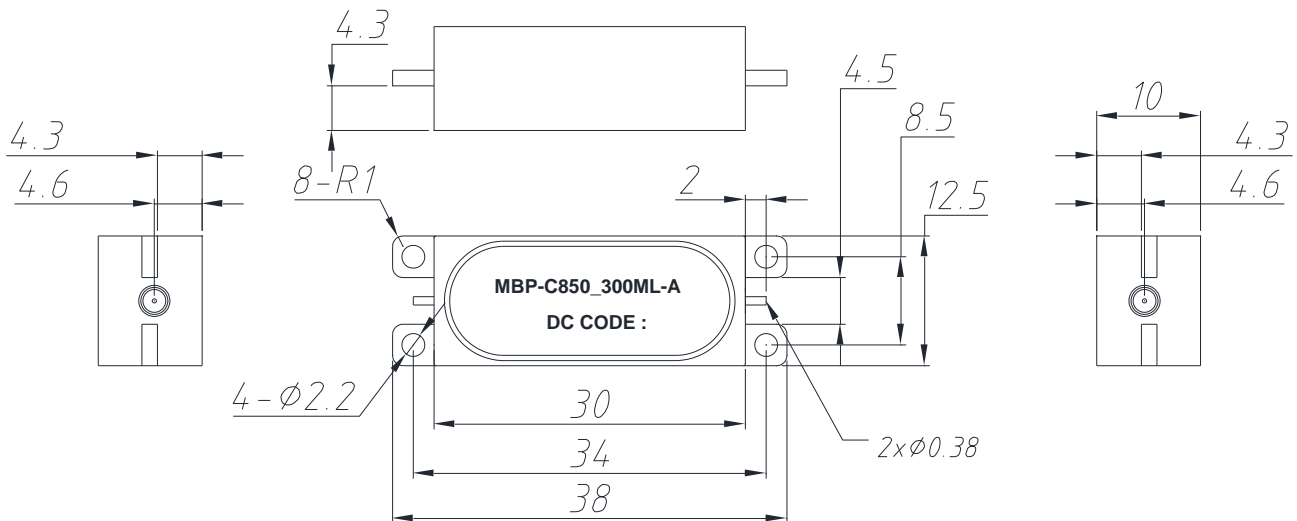
**Product Name : Sub Band1\_2 BPF**

**Part No : MBP-C850\_300ML-A-R4**

### ■ History List

No	Rev. No.	Description	Date	Author	Final Approver
1	R0	Draft	2021.02.24	Bryan Jeon	Michael Jeon
2	R1	Has changed filter dimension and added simulation graph	2021.06.07	Bryan Jeon	Michael Jeon
3	R2	Added glass bead information	2021.06.18	Bryan Jeon	Michael Jeon
4	R3	Added G/D and Phase Specifications	2021.06.25	Bryan Jeon	Michael Jeon
5	R4	Added constraining range And Added test curve	2021.07.08 2021.10.18	Bryan Jeon	Michael Jeon

## ■ Mechanical Drawing



### Note

1. Connector : SMD
2. Pin Plating : Au
3. Pin diameter : 0.38mm
3. Finish : Ag Plating

## ■ Electrical Specification

Parameter	Specification	Remark
1. Center Frequency	850MHz	
2. Frequency Range	C.F.±150MHz[700-1000MHz]	
3. Insertion Loss	2.0dB Max.	
4. Ripple	1.0dB Max.	
5. Return Loss	15dB Min.	
6. Rejection	55dBc Min @ DC ~ 500MHz 55dBc Min @ 1200 ~ 3000MHz	
7. Group Delay Ripple	5ns Max.	
8. Phase	±5%	
9. Size	30.0 x 12.5 x10.0mm	
10. Impedance	50Ω	
11. Operating Temperature	-40 + 85℃	

## ■ Test Curve

